

Solder Wire

Product Description

Lead-free solder wire $\phi 0.8$ specification, good welding fluidity, stable melting point, bright and firm solder joint, environmentally friendly lead-free, suitable for various electronic welding scenarios.



Product Advantages

- Environment-friendly and lead-free
- Good fluidity
- Stable Mel point
- Bright solder joint
- Firm connection

◆ Product Structure

Uniform wire diameter design, core flux filling, tightly wound packaging, anti-oxidation treatment, smooth surface without impurities, easy for precise welding

◆ Application Scenarios

Electronic equipment welding, circuit board production, home appliance maintenance, precision instrument assembly, automotive electronic welding

◆ Technical Features

Wire diameter $\phi 0.8$ mm
 Lead-free composition (Sn99.3% Cu0.7%)
 Melting point 217-227 °C
 Weight 500g/coil
 Protection grade IP65/IP67
 Tensile strength ≥ 30 MPa
 Shear strength of solder joint ≥ 15 MPa

Item#	Weight	Packaging Method
1.4.22.00.0054	0.5kg	Individually wrapped

◆ Remarks

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